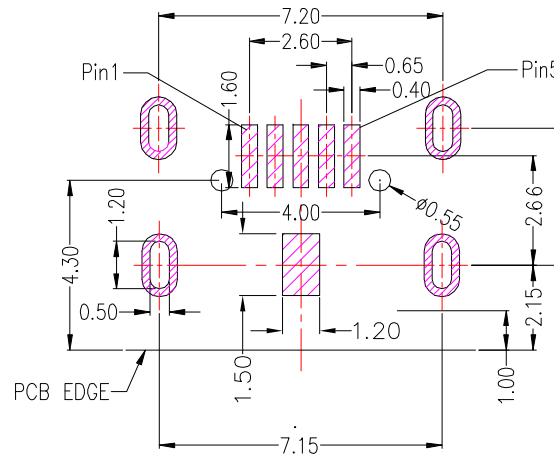
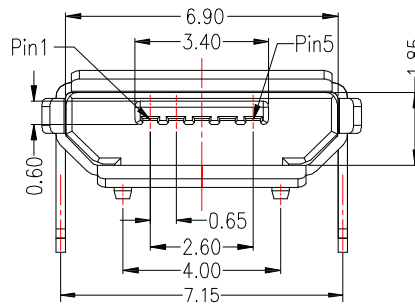
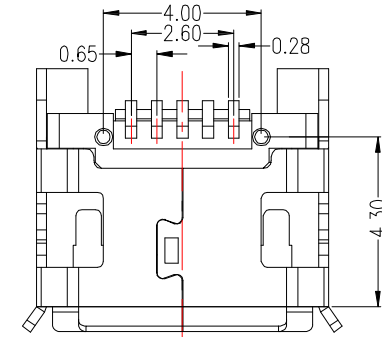
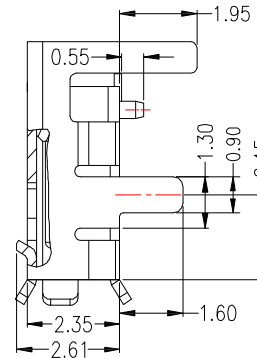
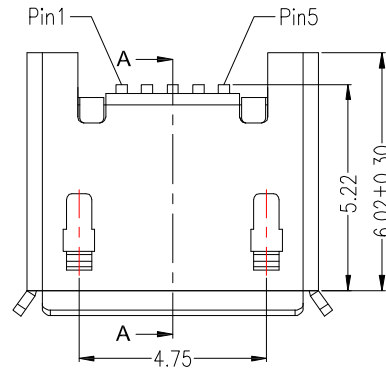


SECTION A-A



P.C.B LAYOUT MOUNTING PATTERN

NOTES:

MATERIAL:

- 1.1 HOUSING: LCP,UL94V-0
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: BRASS

Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A (PIN1&5) MAX,1.0 A (PIN2&3&4) MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 11/17/17
DATE: 11/17/17
DATE: 11/17/17

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	MICRO USB B TYPE SHELL DIPx4: 7.15 ; W/embossing
SCALE	1 : 1	DWG NO.	MRUSB-5B-ED7NI-S347
SHEET NO.	1 of 1	PART NO.	MRUSB-5B-ED7NI-S347
		SIZE	A4
		VER	A3

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	更新PCB LAYOUT	Jack	111717
2	更新PCB LAYOUT尺寸	Jack	062617
1	新增PIN定義	Jack	080816